CLAIMS

1. (Previously presented) A lamination ceramic chip inductor, formed by the process comprising the steps of:

interposing a conductive pattern between a pair of magnetic insulation layers so as to be in contact with the pair of magnetic insulation layers and so that the magnetic insulation layers contact one another in areas not in contact with the conductive pattern; and

forming a conductive coil,

wherein the interposing step includes electroforming at least one conductive pattern, and the conductive pattern has a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

2. (Original) A lamination ceramic chip inductor according to claim 1, wherein the step of interposing at least one conductive pattern includes interposing a plurality of conductive patterns, and wherein the step further comprises printing a thick film conductor to electrically connect at least two of the conductive patterns to each other.

3. (Original) A lamination ceramic chip inductor according to claim 2, wherein the interposing step includes interposing an electroformed conductive pattern having a shape of a straight line.

4. (Canceled)

5. (Original) A lamination ceramic chip inductor according to claim 1, wherein the interposing step includes interposing at least one conductive pattern between

insulation layers formed of a material containing one of a non-shrinkage powder which does not shrink from sintering and a low ratio shrinkage powder which shrinks slightly from sintering.

6. (Previously presented) A lamination ceramic chip inductor according to claim 1, wherein the interposing step includes interposing the at least one conductive pattern between insulation layers formed of a magnetic material containing an organolead compound as an additive for restricting deterioration of magnetic characteristics of the insulating layers.

7. (Original) A lamination ceramic chip inductor according to claim 1, wherein the interposing step includes electroforming the conductive pattern of a silver plating liquid containing no cyanide.

8-27. (Canceled)

28. (Previously presented) A lamination ceramic chip inductor, formed by the process comprising the steps of:

interposing a conductive pattern between a pair of magnetic insulation layers so as to be in contact with at least one of the pair of magnetic insulation layers; and

forming a conductive coil,

wherein the interposing step includes electroforming at least one conductive pattern, and the conductive pattern has a thickness of 10 μm or more and a width to thickness ratio of from 1 to less than 5.

29. (Previously presented) A lamination ceramic chip inductor according to claim 28, wherein the step of interposing at least one conductive pattern includes

interposing a plurality of conductive patterns, and wherein the step further comprises printing a thick film conductor to electrically connect at least two of the conductive patterns to each other.

30. (Previously presented) A lamination ceramic chip inductor according to claim 29, wherein the interposing step includes interposing an electroformed conductive pattern having a shape of a straight line.

31. (Previously presented) A lamination ceramic chip inductor according to claim 28, wherein the interposing step includes interposing at least one conductive pattern between insulation layers formed of a material containing one of a non-shrinkage powder which does not shrink from sintering and a low ratio shrinkage powder which shrinks slightly from sintering.

32. (Previously presented) A lamination ceramic chip inductor according to claim 28, wherein the interposing step includes interposing the at least one conductive pattern between insulation layers formed of a magnetic material containing an organolead compound as an additive for restricting deterioration of magnetic characteristics of the insulating layers.

33. (Previously presented) A lamination ceramic chip inductor according to claim 28, wherein the interposing step includes electroforming the conductive pattern using a silver plating liquid containing no cyanide.

34. (Previously presented) A greensheet, formed by the process consisting essentially of the steps of:

a) forming a first insulation layer;

b) forming a conductive pattern on said first insulating layer;

c) forming a second insulating layer on said conductive pattern;

d) forming a second conductive pattern on said second insulating layer;

e) repeating steps c) and d) to form a plurality of ceramic chip inductors laminated together;

wherein at least one of step b) and d) includes electroforming a conductive pattern, and the conductive pattern has a thickness of 10 μm or more and a width to thickness ratio of from 1 to less than 5.

35. (Currently amended) A ~~lamination ceramic chip inductor~~ greensheet according to claim 34, further comprising printing a thick film conductor to electrically connect at least two of the conductive patterns to each other.

36. (Currently amended) A ~~lamination ceramic chip inductor~~ greensheet according to claim 35, wherein the electroformed conductive pattern is formed in a shape of a straight line.

37. (Currently amended) A ~~lamination ceramic chip inductor~~ greensheet according to claim 34, wherein at least one of the first and second insulating layers is formed of a material containing one of a non-shrinkage powder which does not shrink from sintering and a low ratio shrinkage powder which shrinks slightly from sintering.

38. (Currently amended) A ~~lamination ceramic chip inductor~~ greensheet according to claim 34, wherein at least one of first and second insulating layers is formed of a magnetic material containing an organolead compound as an additive for restricting deterioration of magnetic characteristics of the insulating layers.

39. (Currently amended) A ~~lamination ceramic chip inductor~~ greensheet according to claim 34, wherein at least one of steps a) and c) includes electroforming the conductive pattern using a silver plating liquid containing no cyanide.